

Tim Tilford

List of Publications by Year in descending order

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20
papers

192
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1684188

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times ranked

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citing authors

#	ARTICLE	IF	CITATIONS
1	Lifetime Prediction for Power Electronics Module Substrate Mount-down Solder Interconnect. , 2007, , .		41
2	Wire Bond Reliability for Power Electronic Modules - Effect of Bonding Temperature. , 2007, , .		32
3	Data driven approach to quality assessment of 3D printed electronic products. , 2015, , .		21
4	Design, manufacture and test for reliable 3D printed electronics packaging. Microelectronics Reliability, 2018, 85, 109-117.	1.7	20
5	Optimization of an Open-Ended Microwave Oven for Microelectronics Packaging. IEEE Transactions on Microwave Theory and Techniques, 2008, 56, 2635-2641.	4.6	10
6	Encapsulation of Microelectronic Components Using Open-Ended Microwave Oven. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 799-806.	2.5	10
7	Polymer cure modeling for microelectronics applications. , 2009, , .		9
8	Comparative Reliability of Inkjet-Printed Electronics Packaging. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 351-362.	2.5	9
9	Reliability Testing and Stress Measurement of QFN Packages Encapsulated by an Open-Ended Microwave Curing System. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 173-180.	2.5	6
10	Multi-Material Heatsink Design Using Level-Set Topology Optimization. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 1504-1513.	2.5	6
11	Predictive reliability and prognostics for electronic components: Current capabilities and future challenges. , 2008, , .		5
12	Multi-physics models and condition-based monitoring for 3D-Printing of electronic packages. , 2017, , .		5
13	Modelling methodologies for assessment of 3D inkjet-printed electronics. , 2016, , .		4
14	Predictive modelling for 3D inkjet printing processes. , 2016, , .		4
15	Design of Additively Manufactured Heatsinks for Power Electronics Thermal Management using Adjoint Level-set Topology Optimization. , 2019, , .		4
16	Thermal-mechanical Modelling of Power Electronic Module Packaging. , 2007, , .		3
17	Modelling and optimisation study on the fabrication of nano-structures using imprint forming process. Engineering Computations, 2011, 28, 93-111.	1.4	2
18	Numerical Analysis of the Design and Manufacture of Inkjet Printed Electronics Packaging. , 2018, , .		1

#	ARTICLE	IF	CITATIONS
19	Polymer Curing within an Optimised Open-Ended Microwave Oven. , 2008, , .		0
20	Modelling Technologies and Applications. , 2018, , 45-82.		0